



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB031NE7N3 G		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000851456							
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1464.74 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.048	0.48	0.48	4812	4812	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175		
	non noble metal	copper	7440-50-8	851.691	58.14	58.22	581461	582218	
wire	non noble metal	aluminium	7429-90-5	10.446	0.71	0.71	7132	7132	
encapsulation	organic material	carbon black	1333-86-4	8.709	0.59		5946		
	plastics	epoxy resin	-	95.801	6.54		65404		
	inorganic material	silicondioxide	60676-86-0	476.100	32.50	39.63	325040	396390	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6593	6593	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	non noble metal	tin	7440-31-5	0.079	0.01		54		
	noble metal	silver	7440-22-4	0.099	0.01		67		
	non noble metal	lead	7439-92-1	3.776	0.26	0.28	2578	2699	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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